



8th International Conference on Electronics Packaging Technology (ICEPT 2007)

August 14th – 17th, 2007, Shanghai, China

Since 1994, ICEPT has been held seven times in Beijing, Shanghai and Shenzhen, China. Each ICEPT has attracted hundreds of participants from colleges, research institutes, packaging testing manufacturers, packaging testing equipment factories, packaging materials factories including distinguished experts, scholars and enterprises. The conference is highly focused on semiconductor packaging design, semiconductor packaging manufacturing, semiconductor packaging testing, LED packaging, MEMS packaging, system packaging and assembly. We sincerely invite your participation.

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Topics for ICEPT'2007:
Advanced Packaging & System Packaging: BGA, CSP, flip chip, WLP, nano-packaging, Cu/low-K packaging, 3D packaging, SiP and other advanced packaging and integration technologies.
High Density Substrate & SMT: HDI, PCB, high performance multi-layer substrate, embedded substrate, micro via, microjoin, stencil print, reflow, and other novel assembly technologies that improve substrate density and performance.
Packaging Design & Modeling: novel designs for various packaging/assembly, modeling, simulation and characterization solutions for electrical, thermal, optical & mechanical properties, multi-function & multi-scale modeling, simulation, validation.
Packaging Materials & Processes: interconnection and encapsulation materials including bonding wires, solder balls, solder pastes, conductive pastes, plastic packaging materials, adhesives, thin-films, dielectric materials, frame materials, green electronics.
Advanced Manufacturing Technology: photolithography, laser processing, novel packaging/assembly technologies, advanced methods/software for modeling and monitoring of process effectiveness and cost analysis, and related manufacturing equipment.
Emerging Technologies: sensors, actuators, MEMS, NEMS and MOEMS, optoelectronics & LED packaging, LCD, solid state lighting, passive and RF devices, power & HV devices, nano devices based on nanowire, nanotubes and polymers, etc.
Quality & Reliability: Quality monitoring and evaluation for packaging/assembly, advanced methods/technologies/tools for rapid reliability data collection and analysis system, reliability issues in emerging technologies.

Future Directions in IC and Package Design Workshop (FDIP)

October 28, 2007 Atlanta, GA

Organized by the CPMT TC on Electrical Design, Modeling, and Simulation (TC-EDMS)

Held just prior to the
Electrical Performance of Electronic Packaging Conference
October 29-31, 2007

For full information and to register, visit
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